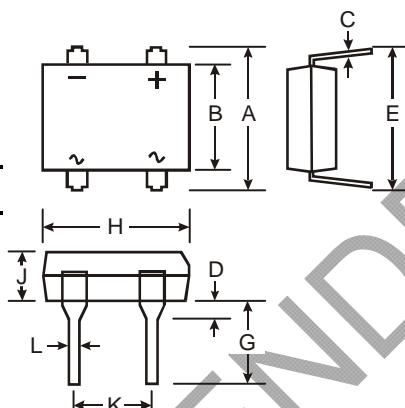


Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop, High Current Capability
- Surge Overload Rating to 50A Peak
- Designed for Printed Circuit Board Applications
- UL Listed Under Recognized Component Index, File Number E94661
- **Lead Free Finish, RoHS Compliant (Date Code 0532+)** (Note 3)

Mechanical Data

- Case: DF-M
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish — Tin. Solderable per MIL-STD-202, Method 208 (Note 3)
- Polarity: As Marked on Case
- Marking: Type Number
- Weight: 0.38 grams (approximate)



DF-M		
Dim	Min	Max
A	7.40	7.90
B	6.20	6.50
C	0.22	0.30
D	1.27	2.03
E	7.60	8.90
G	3.81	4.69
H	8.13	8.51
J	2.40	3.40
K	5.00	5.20
L	0.46	0.58

All Dimensions in mm

Maximum Ratings and Electrical Characteristics

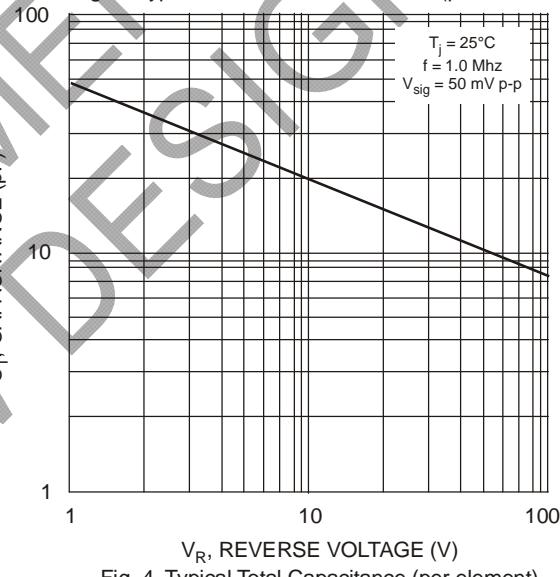
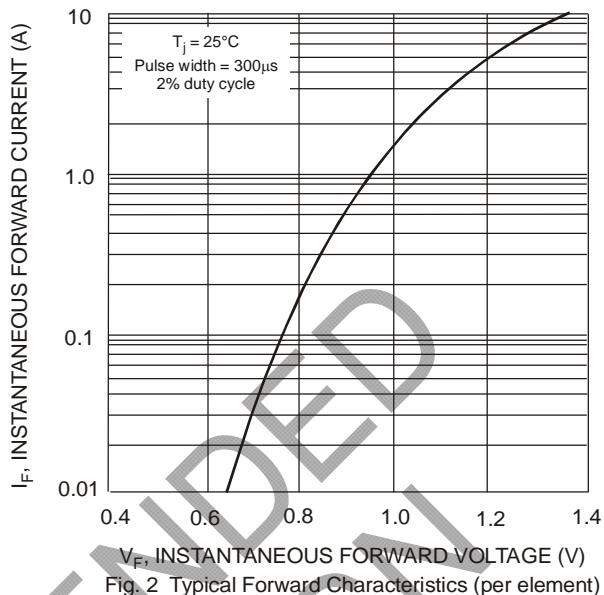
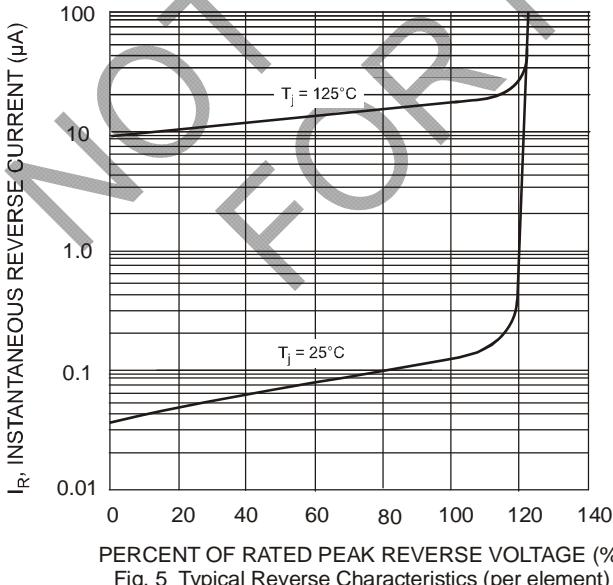
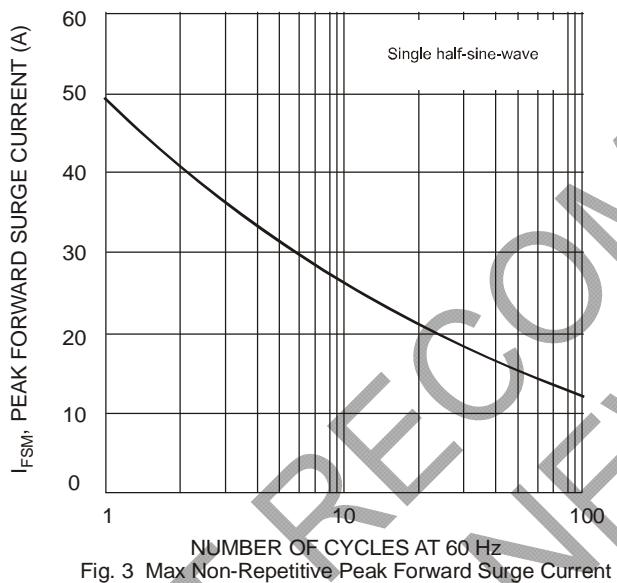
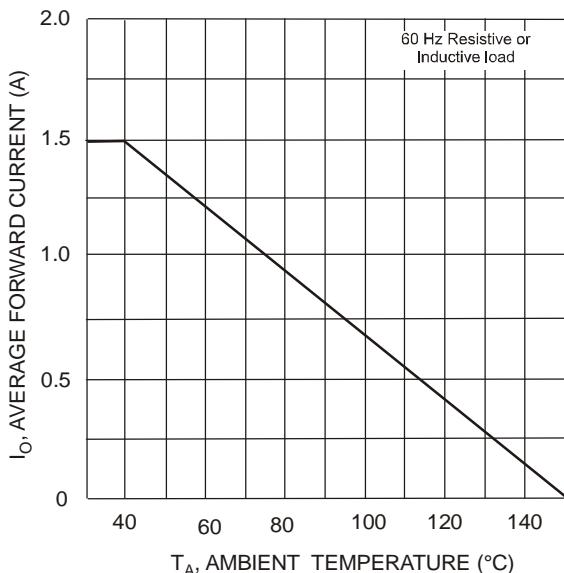
$\text{@ } T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	DF 15005M	DF 1501M	DF 1502M	DF 1504M	DF 1506M	DF 1508M	DF 1510M	Unit
Peak Repetitive Reverse Voltage	V_{RRM}								
Working Peak Reverse Voltage	V_{RWM}	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V_R								
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current $\text{@ } T_A = 40^\circ\text{C}$	I_O				1.5				A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}				50				A
Forward Voltage (per element) $\text{@ } I_F = 1.5\text{A}$	V_{FM}				1.1				V
Peak Reverse Current $\text{@ } T_A = 25^\circ\text{C}$ $\text{@ } T_A = 125^\circ\text{C}$	I_{RM}				10	500			μA
I^2t Rating for Fusing ($t < 8.3\text{ms}$)	I^2t				10.4				A^2s
Typical Total Capacitance (Note 2)	C_T				25				pF
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$				40				$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}				-65 to +150				$^\circ\text{C}$

Notes:

1. Thermal resistance from junction to ambient mounted on PC board with 13 x 13mm (0.03mm thick) land areas.
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.
3. RoHS revision 13.2.2003. Glass and high temperature solder exemptions applied, see EU Directive Annex Notes 5 and 7.



Ordering Information (Note 4)

Device	Packaging	Shipping
DF15xxM	DF-M	50 per Tube

Notes: 4. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 1. are intended to implant into the body, or
 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2010, Diodes Incorporated

www.diodes.com